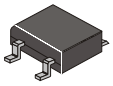
DESCRIPTION and APPLICATIONS

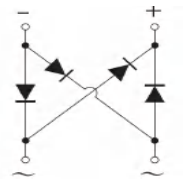
Suitable for AC to DC bridge full wave rectification for SMPS, LED lighting, adapter, battery charger, home appliances, office equipment, and telecommunication applications.

VOLTAGE RANGE
50 to 1000 Volts
CURRENT
0.6 Ampere

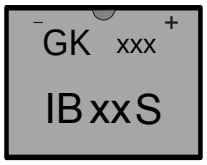
FEATURES

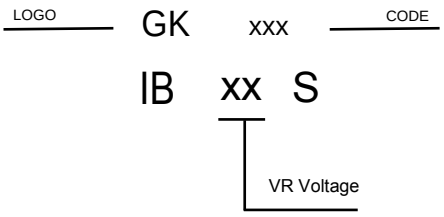
- Glass Passivated Chip Junction
- Reverse Voltage - 100 to 1000V
- Average Rectified Output Current - 0.6A
- High Surge Current Capability
- Designed for Surface Mount Application





Internal Schematic





MECHANICAL DATA

- Case: IBS
- Terminals: Solderable per MIL-STD-750, Method 2026

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

TYPE NUMBER	IB05S	IB1S	IB2S	IB4S	IB6S	IB8S	IB10S	UNIT
Maximum Recurrent Peak Reverse Voltage	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current	0.6							A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	25							A
I^2t Rating for Fusing (1ms < t < 8.3ms)	2.59							A^2S
Maximum Forward Voltage Drop per Bridge Element at 0.3A D.C.	1.0							V
Maximum DC Reverse Current Ta=25°C	5.0							μA
at Rated DC Blocking Voltage Ta=125°C	500							μA
Typical Thermal Resistance $R_{\theta JA}$ (Note 2)	60							°C/W
Operating Temperature Range, T_J	-55 — +150							°C
Storage Temperature Range, T_{STG}	-55 — +150							°C

NOTES: 1. Mounted on P.C. Board.
2. Thermal Resistance Junction to Ambient.

RATING AND CHARACTERISTIC CURVES

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

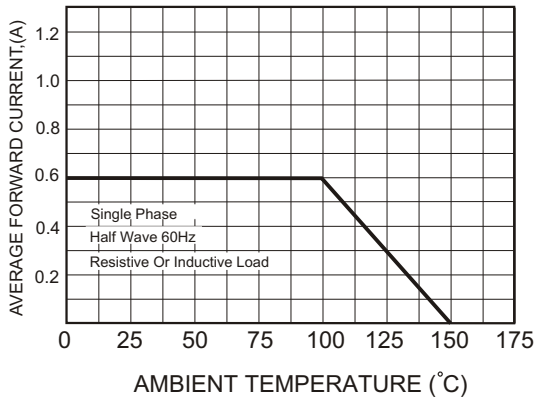


FIG.2-TYPICAL FORWARD CHARACTERISTICS

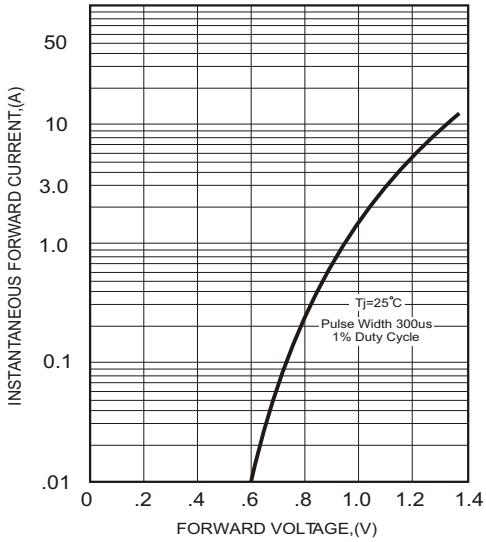


FIG.3 - TYPICAL REVERSE CHARACTERISTICS

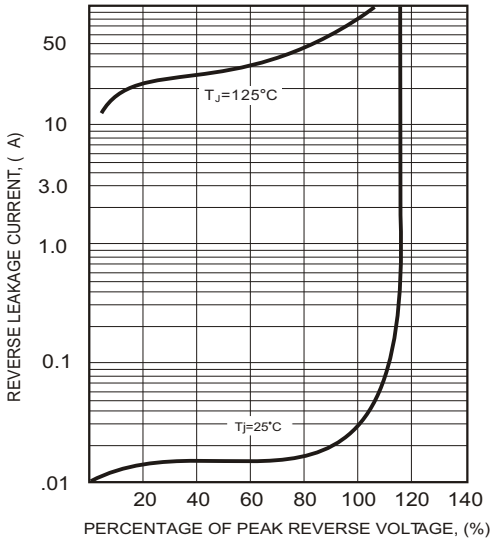
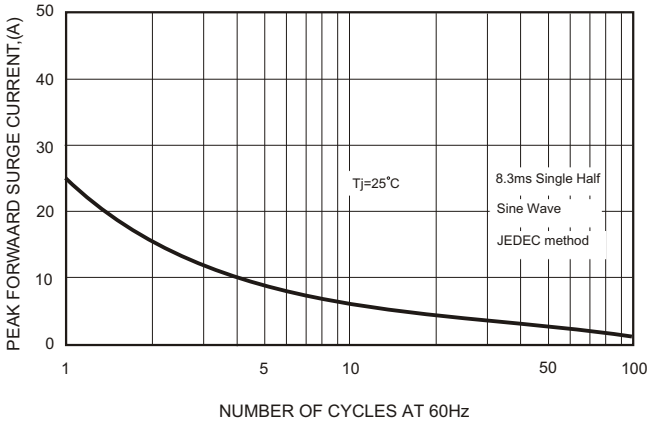


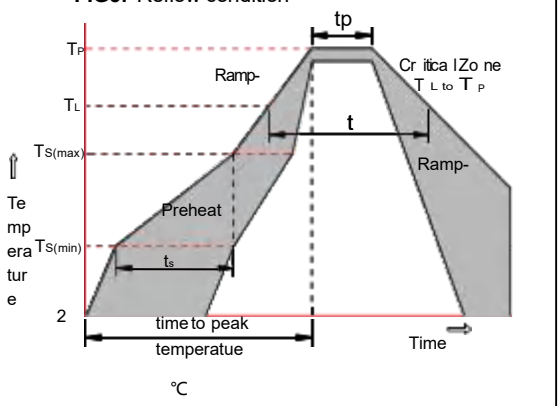
FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT



Soldering parameters

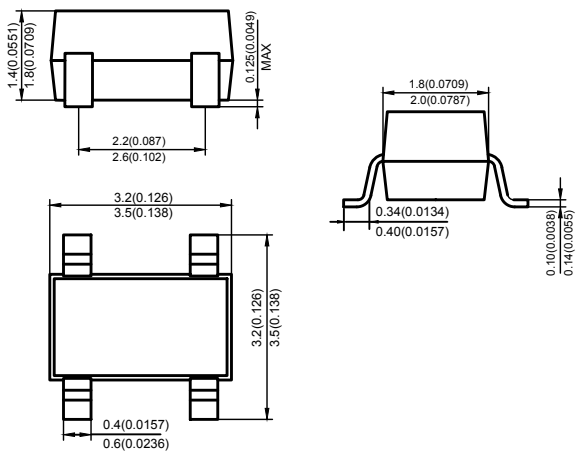
Reflow Condition		Pb-Free assembly (see as bellow)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150℃
	-Temperature Max($T_{s(max)}$)	+200℃
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3℃/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3℃/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217℃
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)℃
Time within 5℃ of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6℃/sec. Max
Time 25℃ to Peak Temp (T_P)		8 min. Max
Do not exceed		+260℃

FIG5: Reflow condition

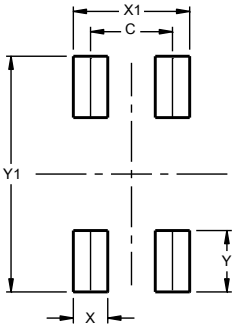


Package Dimensions & Suggested Pad Layout

IBS



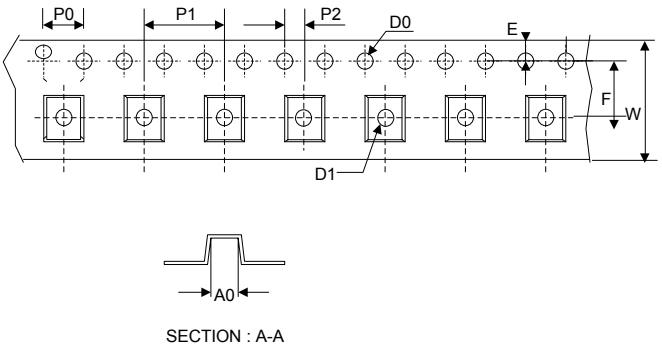
Dimensions in millimeters(inches)



Dimensions	Value (in mm)
C	2.30
X	0.90
X1	3.20
Y	1.20
Y1	4.20

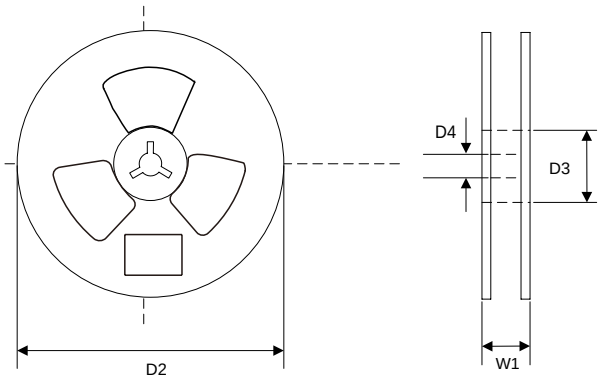
Tape & rell specification

Tape



Symbol	Dimension (mm)
P0	4.00±0.20
P1	4.00±0.20
P2	2.00±0.20
D0	1.55±0.20
D1	1.20±0.20
E	1.55±0.25
F	3.60±0.20
W	8.00±0.20
A0	4.00±0.20
B0	4.00±0.20
K0	2.05±0.20
T	0.20±0.20

13” Reel



D2	330.0±5.0
D3	73Min.
D4	16.0±2.5
W1	18.0±3.0

Quantity: 10000PCS